


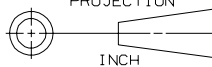
CONTROLLING DIMENSION: INCH

MIL/AERO  
CONFIGURATION CONTROL

NOTES: UNLESS OTHERWISE SPECIFIED

1. LEAD FINISH TO BE ONE OF THE FOLLOWING:
  - a) 200 MICROINCHES/5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
  - b) 50 TO 225 MICROINCHES/1.27 TO 5.72 MICROMETERS GOLD OVER 50 TO 350 MICROINCHES/1.27 TO 8.89 MICROMETERS NICKEL UNDERPLATE.
2. REFERENCE JEDEC REGISTRATION MS-015, VARIATION CA, DATED 7/90.

REVISIONS				
LTR	DESCRIPTION	E. C. N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	10324	02/15/94	MS/

APPROVALS	DATE	 NATIONAL SEMICONDUCTOR CORPORATION 2900 Semiconductor Drive, Santa Clara, CA 95052-8090			
DRAWN MARTA SUCHY	02/15/94	DIP, SIDEBRAZED, CERAMIC, 24 LEAD, DUAL CAVITY, .600 CTRS			
DFTG. CHK.					
ENGR. CHK.					
APPROVAL		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	B	MKT-DA24B	A
 PROJECTION INCH [MM]		DO NOT SCALE DRAWING		SHEET 1 OF 1	